
規格承認書

客户名称 : _____
客户料号 : _____
翱龙料号 : AL998G
送樣日期 : _____

簽程:		客戶確認簽程:	
工程:	胡瑞明	工程:	
品管:	王德力	品管:	
日期:	2021-2-18	日期:	

● **Features:**

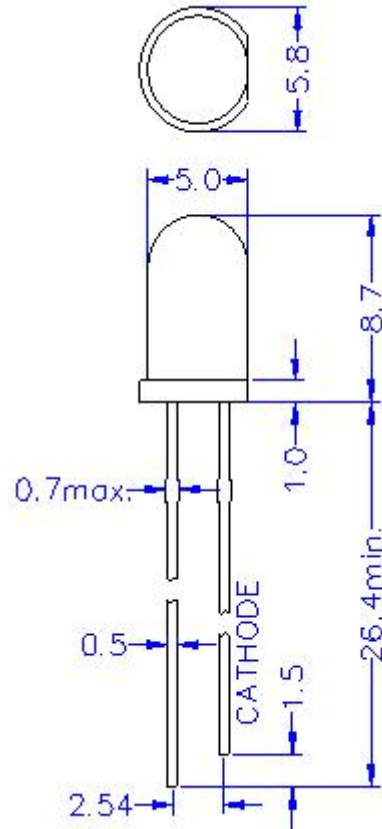
1. Wide range of collector current
2. High photo sensitivity
3. Small junction capacitance
4. Pb free
5. The product itself will remain within RoHS compliant version
6. Lens color: Green

● **Descriptions**

1. The device is a phototransistor in miniature DIP package which is flat top view lens
2. The device is Spectrally matched to visible and infrared emitting diode

● **Applications:**

1. Remote Control.
2. Automatic Control System.



● **Absolute Maximum Ratings(Ta=25°C)**

Parameter	Maximum Rating	Unit
Power Dissipation	100	mW
Collector- Emitter Voltage	30	V
Emitter- Collector Voltage	5	V
Operating Temperature	-45°C~+85°C	
Storage Temperature Range	-45°C~+100°C	
Lead Soldering Temperature	260°C for 5 seconds	

*1 Condition for is I_{FP} pulse of 1/10 duty and 0.1 msec width.

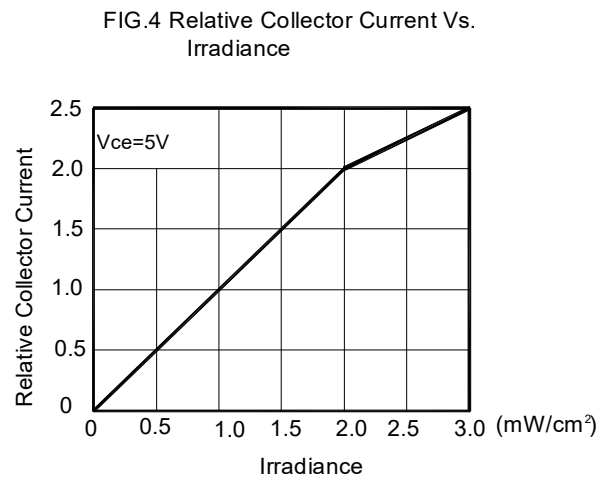
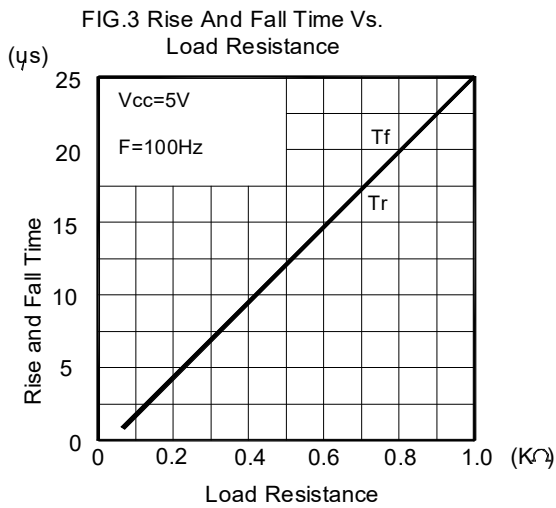
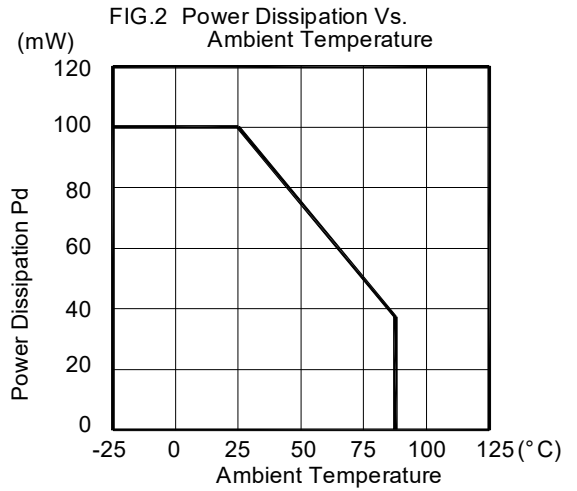
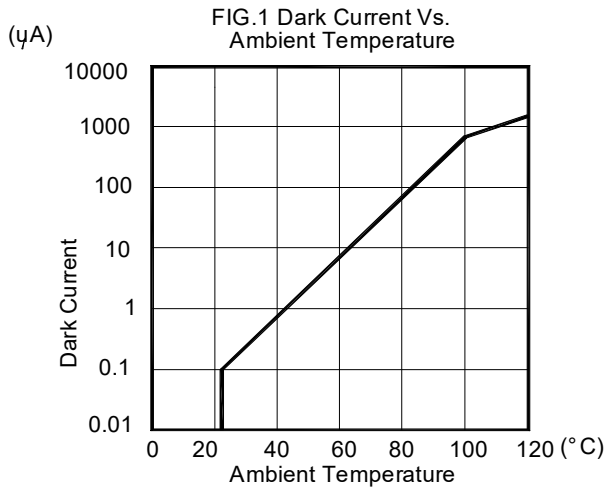
● Optical- Electrical Characteristics (@TA=25°C)

Parameter 参数	Symbol 符号	Rating 数值	Unit 单位
Power Dissipation 耗散功率	PD	100	mW
Reverse Voltage 反向耐压	VRP	5	V
Forward current 正向电流	IF	30	mA
Peak Current(1/10Duty Cycle,0.1ms Pulse Width.) 峰值电流 (1 / 10duty 周期, 脉宽 0.1ms。)	IF(Peak)	50	mA
Operating Temperature Range 工作温度范围	Topr.	-35 to +80	°C
Storage Temperature Range 储存温度范围	Tstg.	-40 to +85	°C
ESD Withstand limit 静电耐受极限	ESD	3000	V
Soldering temperature 焊锡温度	Tsol	260°C Wave soldering, 3mm out of physical body, ≤3S 波峰焊 260°C 离胶体 3 mm, 小于或等于 3 秒	°C

Typical Electrical & Optical Characteristics(Ta=25°)典型的光电特性(Ta=25°)

Items 项目	Symbol 符号	Condition 条件	Min 最小	Typ 典型	Max 最大	Unit 单位
Forward Voltage 正向电压	VF	IF =20mA	3.0	---	3.4	V
Dominant Wavelength 主波长	λ_d	IF =20mA	520	525	530	K
Luminous Intensity 发光强度	Iv	IF =20mA	150	300	---	mcd
View Angle 法向角度	2 θ 1/2	IF =20mA	---	30	---	Deg
Reverse Current 反向电流	IR	Vr=5V	---	---	10	μ A

● **Typical Optical-Electrical Characteristic Curves**

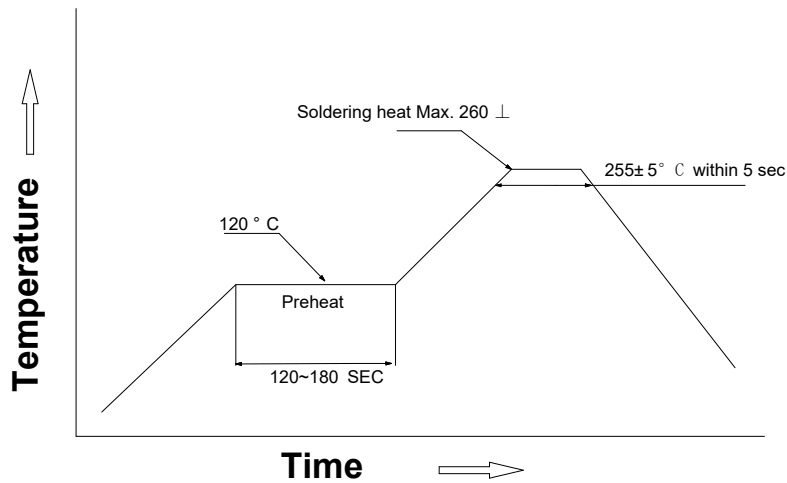


● **Soldering Condition:**

Preheating : 120°C, Within 120°C~180°C sec.

Operation heating : 255°C±5°C Within 5 sec. 260°C (Max)

Gradual Cooling (Avoid quenching).



1. Reflow soldering should not be done more than two times.
2. When soldering, do not put stress on the LEDs during heating.
3. After soldering, do not warp the circuit board.

● Use matters needing attention

- store and use where there is no force causing transformation or change in quality
- store and use where there is no extreme humidity
- in order to prevent damage from static electricity make sure that the human body and the Soldering iron are connected to ground before using
- Please from the bottom of the resin for welding for more than 2 mm
- Dip soldering: please below 260 degrees, 5 seconds to complete welding
- Soldering iron: please below 350 degrees, 3 seconds to complete welding
- Please avoid correct position after welding
- When welding in the lead frame please don't put pressure on the heated condition
- When the circuit board is installed, the mounting hole distance is consistent With the lead frame